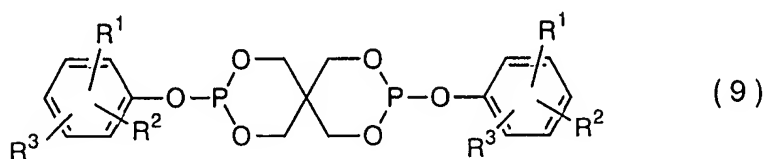


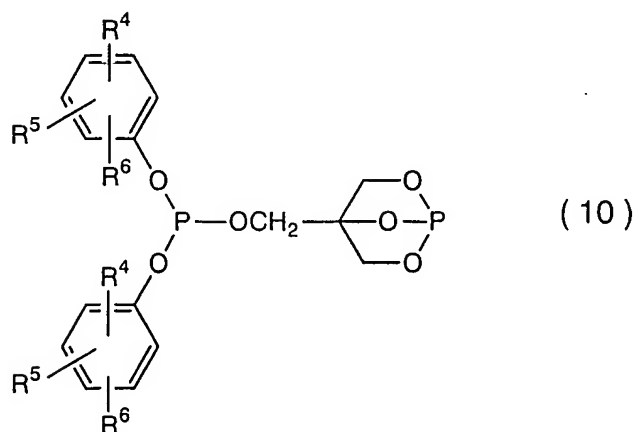
AMENDMENTS TO THE SPECIFICATION**IN THE SPECIFICATION:****Page 20**

Please amend the paragraph on page 20 beginning at line 7 as follows:

In addition, other example compounds as the phosphoric antioxidant, ~~such as bis(dialkylphenyl)pentaerythritol diphosphite ester~~, include a spiro-type compound represented by formula (9) below:



(wherein R¹, R² and R³ represent independently a hydrogen atom or an alkyl group of a carbon number of from 1 to about 9), and a cage-type compound represented by formula (10) below:



(wherein R⁴, R⁵ and R⁶ represent independently a hydrogen atom or an alkyl group of a carbon number of from 1 to about 9).

Page 31

Please amend the paragraph on page 31 beginning at line 20 as follows:

As components (A), (B) and ~~(D)~~ (C), the following components were used. An MFR (melt flow rate) value was measured under the conditions of 2160 g load at a temperature of 190 °C, in accordance with JIS-K7210.

Page 33

Please amend the paragraph on page 33 beginning at line 5 as follows:

EXAMPLE 1

(1) <Production Example of thermosetting resin composition>

Components A-1 (1 part), B-1 (100 parts), ~~D-1~~ C-1 (0.1 part), ~~D-2~~ C-2 (0.1 part) and ~~D-3~~ C-3 (0.05 part) were blended in dry, the resulting mixture was fed to a co-rotating biaxial extruder (L/D = 42) of ϕ 30 mm, and was melt-kneaded at a screw rotational frequency of 180 rpm and a feed speed of 16 Kg/hr under a temperature of 120°C to obtain a thermosetting resin composition.

Page 36

Please amend the paragraph on page 36 beginning at line 4 as follows:

A thermosetting resin composition, an adhesive film having a thickness of about 50 μ m and a laminate were obtained in the same manner as in EXAMPLE 1 except that only

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Component B-1 was used without using component (A) and ~~component (B)~~ component (C). The results of the solder heat resistance test and the peeling test are shown in Table 1.